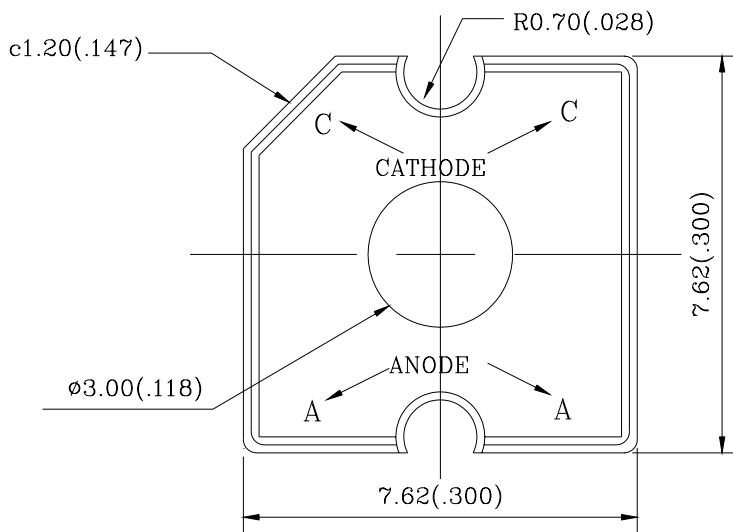




HIGH POWER LED LAMP

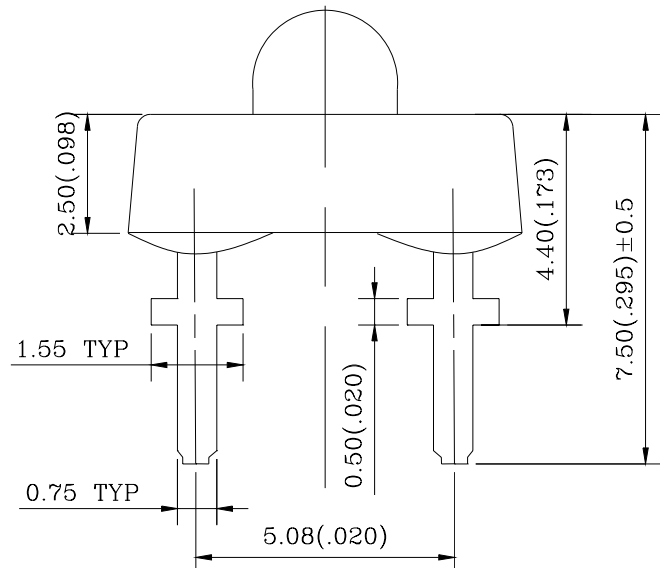
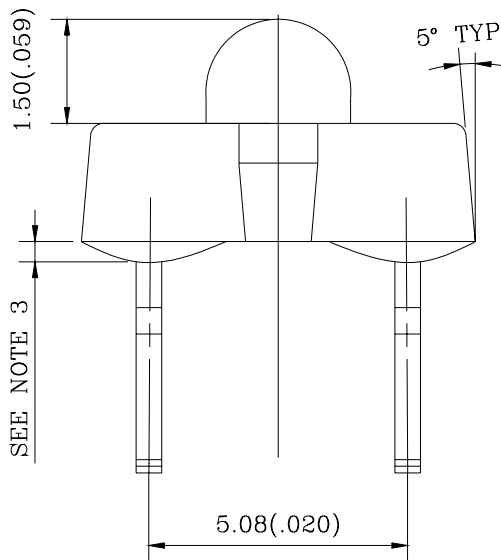
L-945VE6C

PACKAGE DIMENSIONS



Note:

1. All Dimensions are in millimeters.
2. Tolerance is $\pm 0.25\text{mm} (0.010 \text{ "})$ Unless otherwise specified.
3. Protruded resin under flange is $1.5\text{mm} (0.059 \text{ "})$ max.
4. Lead spacing is measured where the leads emerge from the package.
5. Specification are subject to change without notice





HIGH POWER LED LAMP

L-945VE6C

FEATURES

- * HIGH POWER LED LAMP
- * HIGH FLUX OUTPUT
- * DESIGNED FOR HIGH CURRENT OPERATION
- * LOW THERMAL RESISTANCE
- * LOW PROFILE
- * RELIABLE
- * PACKAGED IN TUBES FOR USE WITH AUTOMATIC INSERTION EQUIPMENT

CHIP MATERIALS

- * Dice Material : AlGaInP/GaP
- * Light Color : ULTRA ORANGE
- * Lens Color : WATER CLEAR

ABSOLUTE MAXIMUM RATING : (Ta = 25°C)

SYMBOL	PARAMETER	ORANG. RED	UNIT
PAD	Power Dissipation Per Chip	200	mW
VR	Reverse Voltage Per Chip	5	V
IAF	Continuous Forward Current Per Chip	70	mA
—	Derating Linear From 25°C Per Chip	0.40	mA/°C
Topr	Operating Temperature Range	-25°C to 85°C	
Tstg	Storage Temperature Range	-40°C to 85°C	

Lead Soldering Temperature { 1.6mm(0.063 inch) From Body } 260°C ± 5°C for 5 Seconds

ELECTRO-OPTICAL CHARACTERISTICS : (Ta = 25°C)

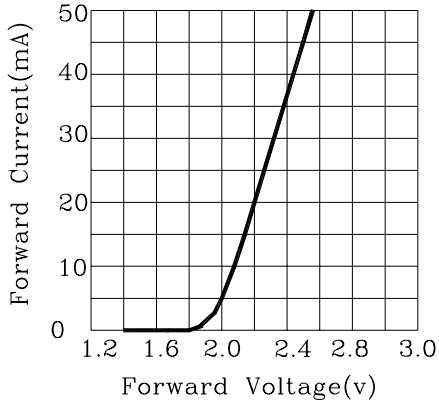
SYMBOL	PARAMETER	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
VF	Forward Voltage	IF = 20mA		2.0	2.6	V
IR	Reverse Current	VR = 5V			10	μA
λD	Dominant Wavelength	IF = 20mA		624		nm
Δλ	Spectral Line Half-Width	IF = 20mA		20		nm
2θ1/2	Half Intensity Angle	IF = 20mA		70		deg
ΦV	Total flux	IF = 70mA		6700		mlm



HIGH POWER LED LAMP

L-945VE6C

Forward Current Vs Forward Voltage



Forward Current VS Relative intensity

